

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
100V	8.5mΩ@10V	65A
	11mΩ@4.5V	



合肥矽普半导体

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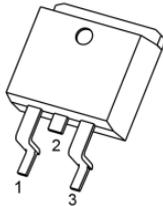
Feature

- Fast Switching
- Low Gate Charge and Rdson
- Advanced Split Gate Trench Technology
- 100% Single Pulse avalanche energy Test

Applications

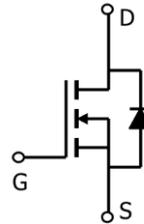
- Power switching application
- PWM Application
- DC-DC Converter

Package

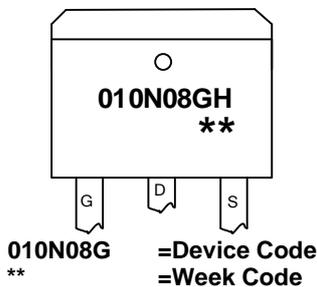


TO-263(1:G 2:D 3:S)

Circuit diagram



Marking



Order Information

Device	Package	Unite/Tape
SP010N08GTD	TO-263-3L	800

Absolute maximum ratings (Ta=25°C unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current (Tc=25°C)	I_D	65	A
Pulsed Drain Current ²	I_{DM}	260	A
Single Pulse Avalanche Energy ³	E_{AS}	156	mJ
Total Power Dissipation ⁴ (Tc=25°C)	P_D	90	W
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	1.38	°C/W
Storage Temperature Range	T_{STG}	-55 to 150	°C
Operating Junction Temperature Range	T_J	-55 to 150	°C

Electrical characteristics (Ta=25°C, unless otherwise noted)

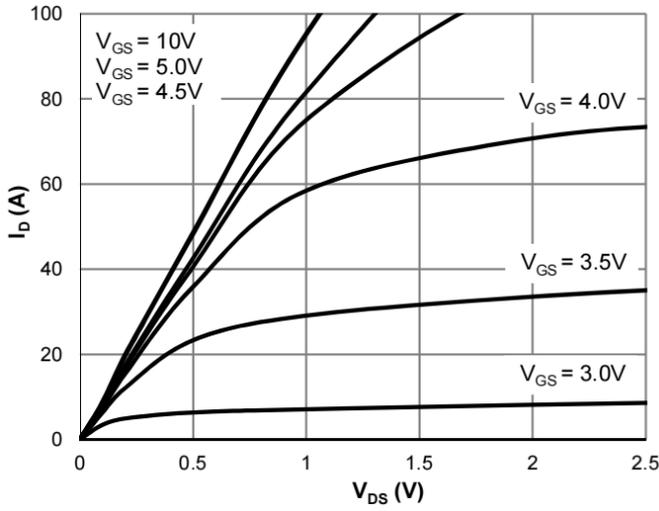
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	100	---	---	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=80V, V_{GS}=0V, T_J=25^\circ C$	---	---	1	μA
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.9	2.5	V
Static Drain-Source On-Resistance ²	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$	---	8.5	12	m Ω
		$V_{GS}=4.5V, I_D=15A$	---	11	15	
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=50V, V_{GS}=0V, f=1MHz$	---	1635	---	pF
Output Capacitance	C_{oss}		---	339	---	
Reverse Transfer Capacitance	C_{rss}		---	22	---	
Switching Characteristics						
Total Gate Charge (4.5V)	Q_g	$V_{DS}=50V, V_{GS}=10V, I_D=20A$	---	14	---	nC
Gate-Source Charge	Q_{gs}		---	5	---	
Gate-Drain Charge	Q_{gd}		---	7	---	
Turn-On Delay Time	$T_{d(on)}$	$V_{DD}=50V, V_{GS}=10V, R_L=2.5\Omega, R_G=6\Omega$	---	8	---	ns
Rise Time	T_r		---	16	---	
Turn-Off Delay Time	$T_{d(off)}$		---	31	---	
Fall Time	T_f		---	27	---	
Source-Drain Diode Characteristics						
Diode Forward Voltage ²	V_{SD}	$V_{GS}=0V, I_S=1A, T_J=25^\circ C$	---	---	1.2	V

Note :

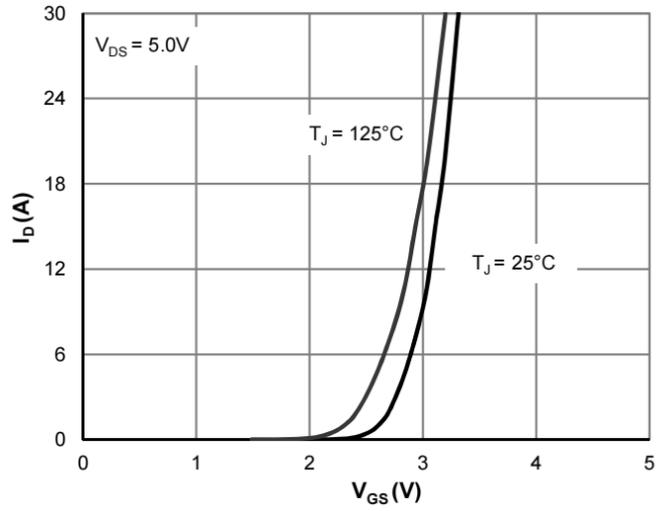
- The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- The EAS data shows Max. rating. The test condition is $V_{DD}=50V, V_{GS}=10V, L=0.5mH, R_g=25\Omega$
- The power dissipation is limited by 150°C junction temperature



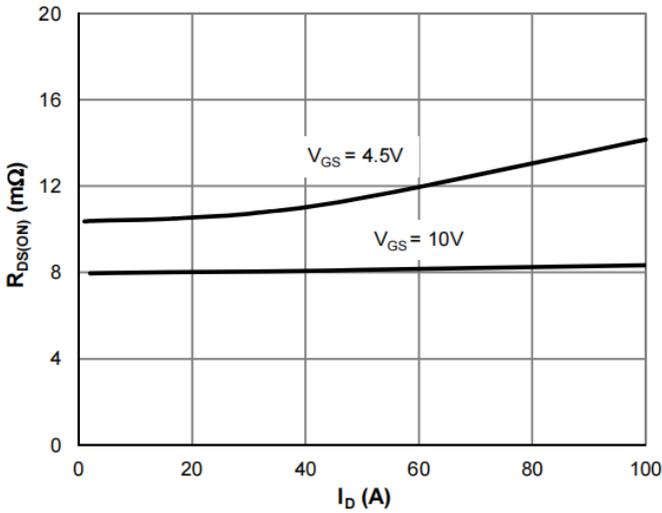
Typical Characteristics



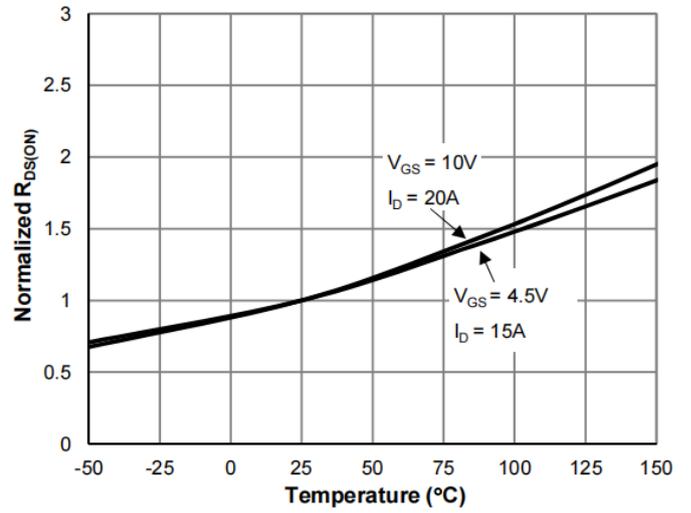
Typical Output Characteristics



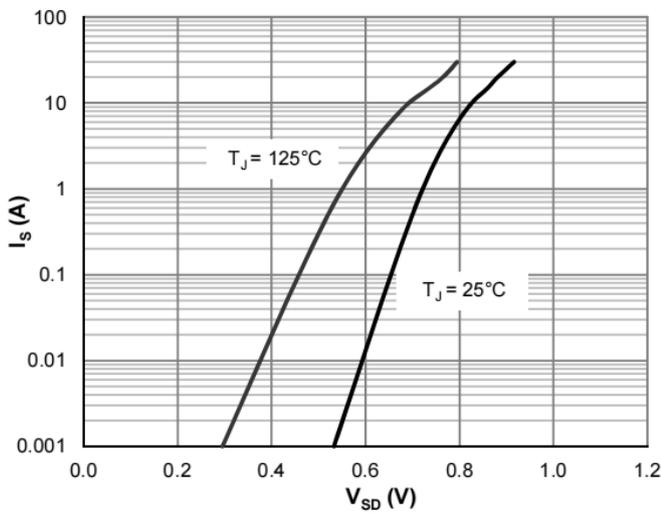
Transfer Characteristics



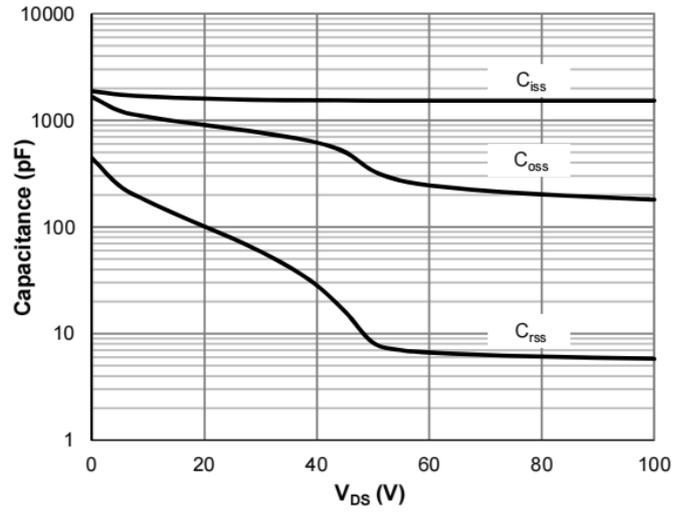
On-Resistance vs. Drain Current



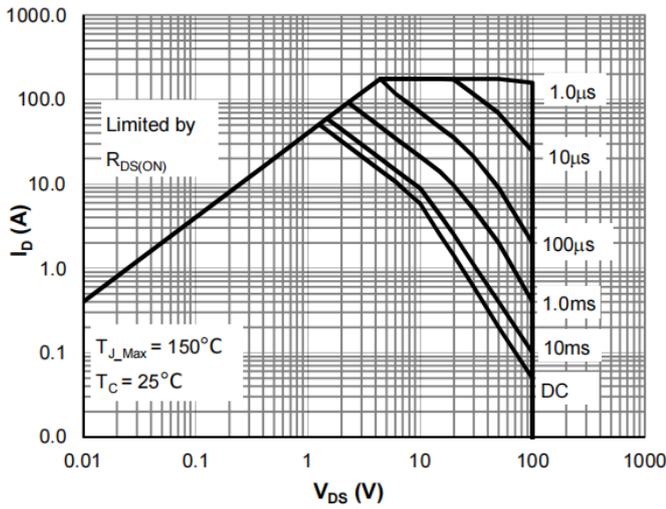
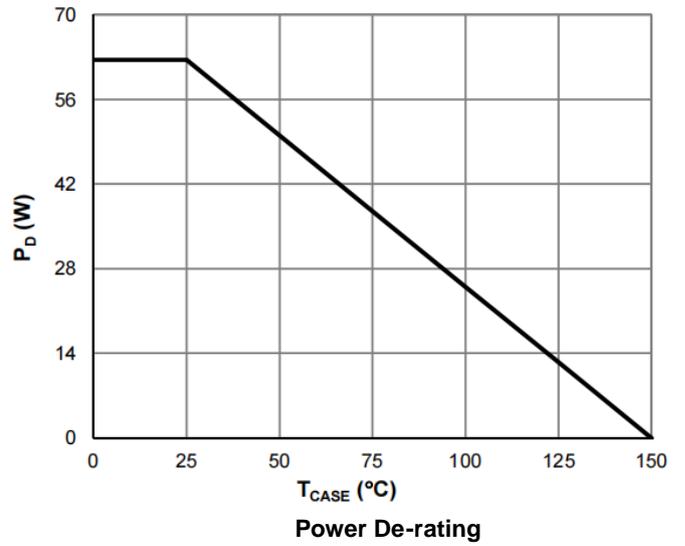
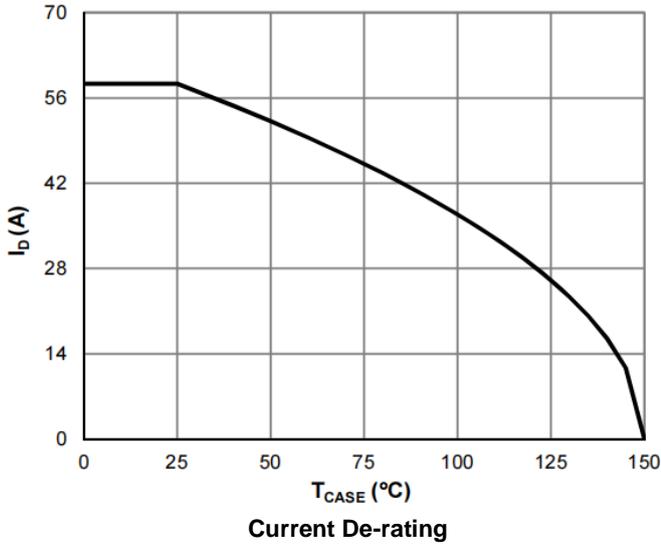
On-Resistance vs. Junction Temperature



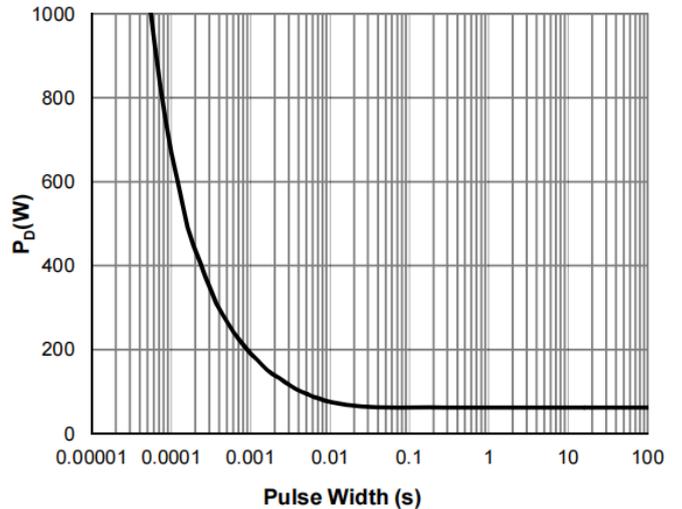
Body-Diode Characteristics



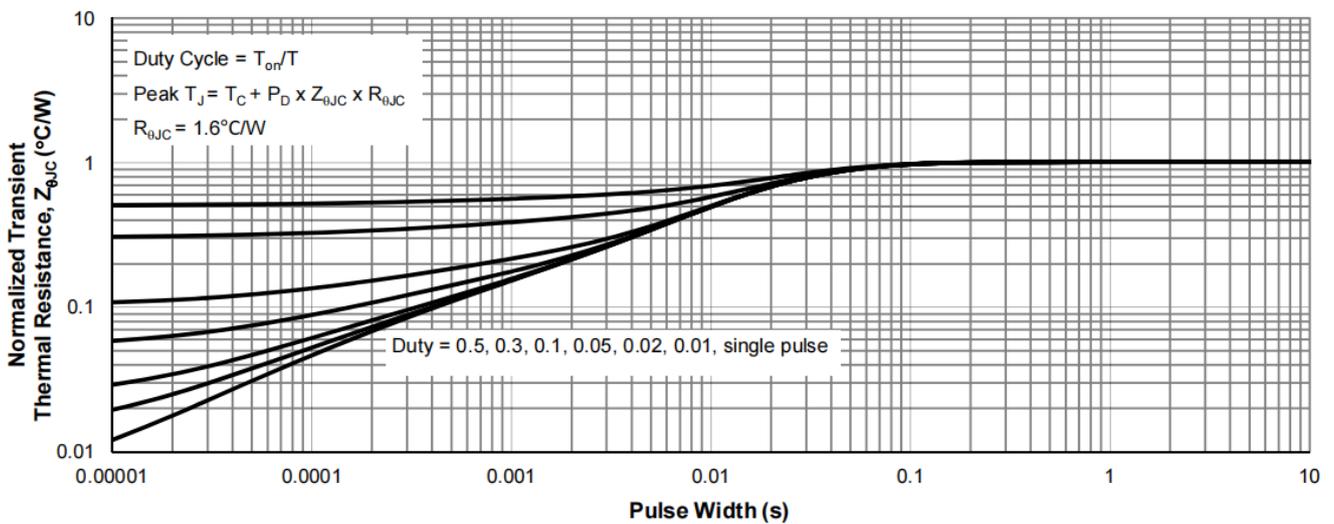
Capacitance Characteristics



Maximum Safe Operating Area



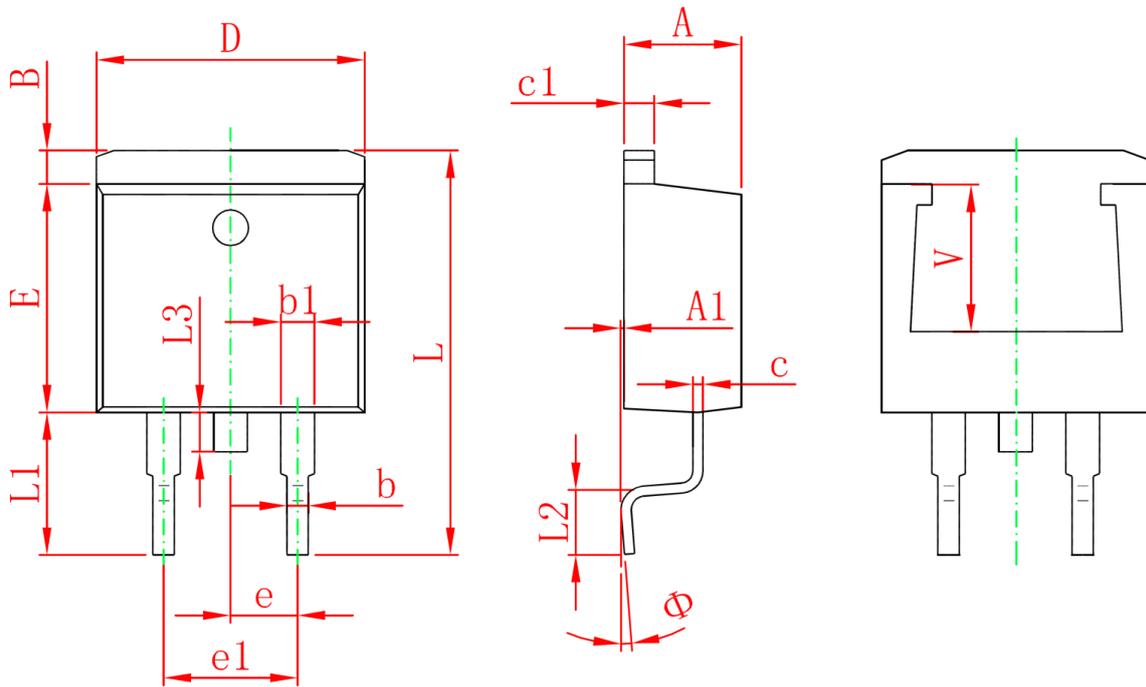
Single Pulse Power Rating, Junction-to-Case



Normalized Maximum Transient Thermal Impedance



TO-263 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.470	4.670	0.176	0.184
A1	0.000	0.150	0.000	0.006
B	1.120	1.420	0.044	0.056
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.310	0.530	0.012	0.021
c1	1.170	1.370	0.046	0.054
D	10.010	10.310	0.394	0.406
E	8.500	8.900	0.335	0.350
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
L	14.940	15.500	0.588	0.610
L1	4.950	5.450	0.195	0.215
L2	2.340	2.740	0.092	0.108
L3	1.300	1.700	0.051	0.067
Φ	0°	8°	0°	8°
V	5.600 REF.		0.220 REF.	